

**REMARKS**

In the present Amendment, claims 1, 2, 8, 9 and 10 have been amended to improve their form. Section 112 support for the amendments may be found, for example, in the original claims and Figure 2. No new matter has been added, and entry of the Amendment is respectfully requested.

Upon entry of the Amendment, claims 1-12 will be pending.

As an initial matter, Applicant respectfully requests the Examiner to acknowledge Applicant's claim for foreign priority and to confirm that the certified copy of the priority document, which was submitted on December 30, 2004, has been received.

In paragraph No. 2 of the Action, claims 1-12 are rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by Saito (US 2002/0048156 A1).

Applicant submits that this rejection should be withdrawn because Saito does not disclose or render obvious the flexible wiring substrate or the method for producing a flexible wiring substrate of the present claimed invention.

Saito discloses a flexible wiring substrate in which a predetermined wiring of copper **112** is formed on the upper surface of an elongated base film **101** in a wiring forming area as a width-directional central portion of the base film **101** and band-shaped first reinforcing layers of copper **113** are formed on width-directional opposite portions of the upper surface of the base film **101** (abstract, [0056] and Figure 8). The copper wiring **112** and the first reinforcing layers of copper **113** are formed by wet etching the same copper film **102** which was originally formed on the base film **101** ([0050], [0055] and [0056]). Subsequently, tin plate layers **115** and **116** are formed on the wiring **112** and the first reinforcing layers **113**, respectively ([0057] and Figure 9). Finally, protective films **118** made of a solder resist in the form of a rectangular frame are

provided on a central portion of each wire **112** and predetermined portions near the central portions ([0058] and Figures 10, 13 and 14).

Saito does not disclose “the uncovered terminal portions of the wiring pattern have a tin-bismuth alloy plating layer which is formed on the surface of the wiring pattern” as recited in present claim 1 as amended. The Office Action takes the position that the tin plate layers **115** and **116** in Saito are a tin-bismuth alloy plating layer as recited in present claim 1. With due respect, Applicant submits that the Office Action’s position is unreasonable, since the tin plate layers **115** and **116** of Saito correspond to a first tin plating layer (24 in Fig 2 of the present application) recited in present claim 1 and present claim 1 recites an additional element that the claimed flexible wiring substrate comprises a tin-bismuth alloy plating layer formed on a surface of the wiring pattern where a solder resist is not formed.

As nowhere in Saito is taught that the flexible wiring substrate has the tin-bismuth alloy plating layer (exemplified by 26 in Fig. 2) formed on a surface of the wiring pattern (exemplified by 11 in Fig. 2) where a solder resist (exemplified by 17 in Fig. 2) is not formed, and nowhere in Saito is taught a step of forming a second tin plating layer on the second region of the first tin plating layer, and a step of providing a tin-bismuth alloy plating layer on at least a portion of the region of the second tin plating layer as recited in present claim 10 as amended, the present claims are not anticipated by Saito.

In view of the above, reconsideration and withdrawal of the § 102(b) rejection based on Saito are respectfully requested.

Allowance is respectfully requested. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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